

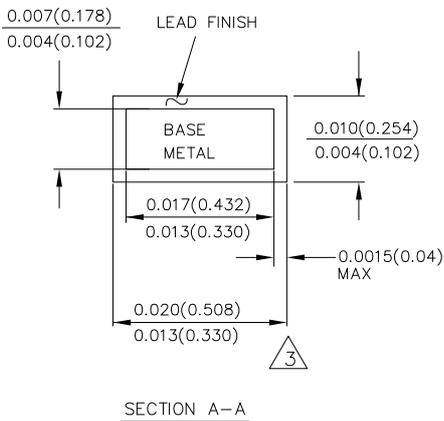
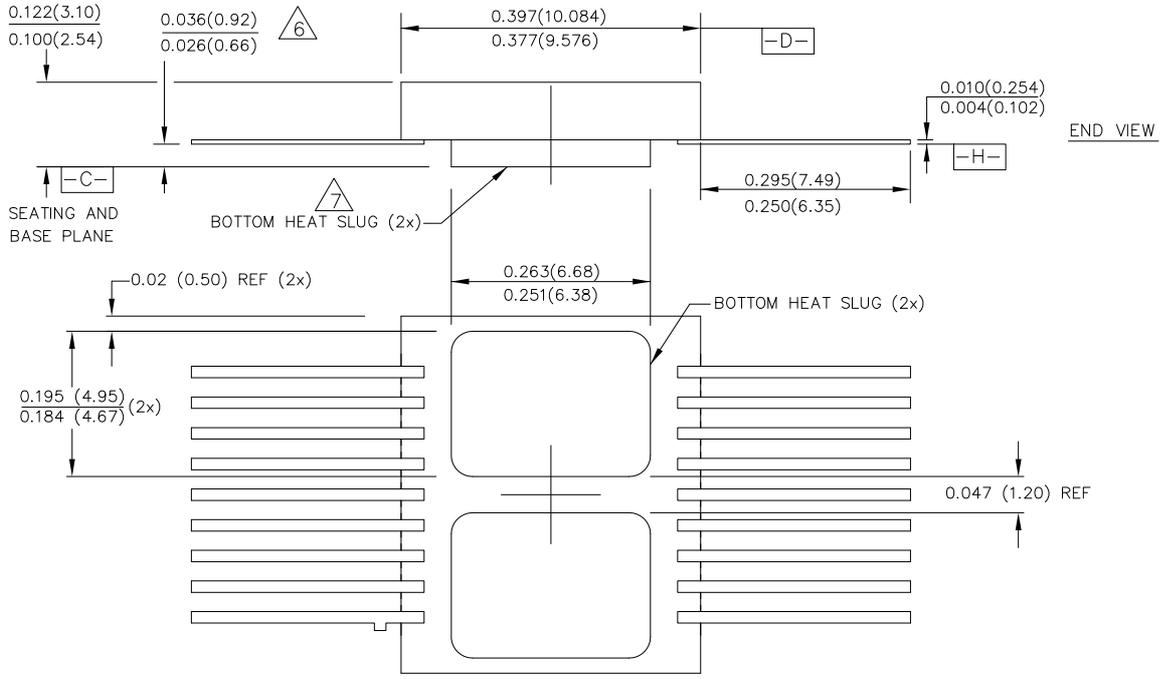
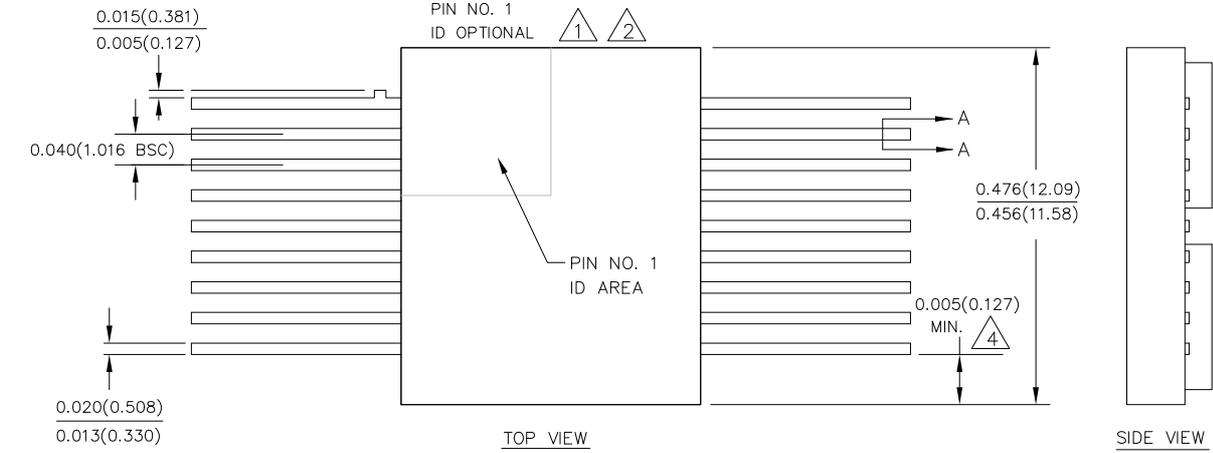
Ceramic Packages for Integrated Circuits

Package Outline Drawing

K18.F

18 Lead Ceramic Metal Seal Flatpack Package with Two Bottom Heat Slugs

Rev 0, 4/2023



- NOTES:
1. Index area: A notch or a pin one identification mark is located adjacent to pin one and is located within the shaded area shown. The manufacturer's identification shall not be used as a pin one identification mark. Alternately, a tab may be used to identify pin one.
 2. If a pin one identification mark is used in addition to a tab, the limits of the tab dimension do not apply.
 3. The maximum limits of lead dimensions (section A-A) are measured at the centroid of the finished lead surfaces, when solder dip or tin plate lead finish is applied.
 4. Measure dimension at all four corners.
 5. For bottom-brazed lead packages, no organic or polymeric materials are molded to the bottom of the of the package to cover the leads.
 6. Dimension is measured at the point of exit (beyond the meniscus) of the lead from the body. Dimension minimum is reduced by 0.0015 inch (0.038mm) maximum when solder dip lead finish is applied.
 7. The bottom of the package consists of two solderable metal heat slugs.
 8. Dimensioning and tolerancing per ANSI Y14.5M - 1982.
 9. Dimensions = INCH (mm). Controlling dimension: INCH.